



Integrated Device Technology, Inc.

12 x 12 BIT PARALLEL CMOS MULTIPLIER

IDT7212L
IDT7213L

FEATURES:

- 12 x 12 parallel multiplier with double precision product
- High-speed — 30ns maximum clock to multiply time
- Low-power consumption — 150mW typical, less than 1/10th the power of compatible bipolar parts
- Produced with advanced CEMOS™ high-performance technology
- IDT7212L is pin and functionally compatible with TRW MPY012H
- IDT7213L requires only a single clock with register enables
- Configured for easy array expansion
- User-controlled option for transparent output register mode
- Round control for rounding the MSP
- Single 5V power supply
- Input and output directly TTL-compatible
- Three-state output
- Available in DIP, SHRINK-DIP, plastic DIP, LCC or Flatpack
- Military product available 100% screened to MIL-STD-883, Class B

DESCRIPTION:

The IDT7212/IDT7213 are high-speed, low power 12 x 12 multipliers ideal for fast, real-time digital signal processing applications. Utilization of a modified Booths algorithm and IDT's high-performance, high-reliability technology, CEMOS, has achieved speeds (30ns max.) exceeding bipolar at 1/10th the power consumption.

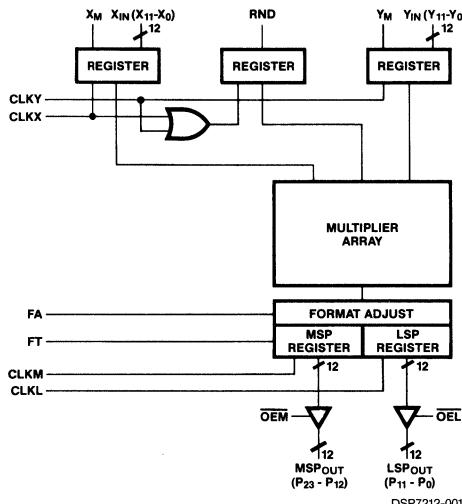
The IDT7212/IDT7213 are ideal for applications requiring high-speed multiplications such as fast Fourier transform analysis, digital filtering, graphic display systems, speech synthesis and recognition, and in any system requirement where multiplication speeds of a mini/micro computer are inadequate.

All input registers, as well as LSP and MSP output registers, use the same positive edge triggered D-type flip-flop. With the IDT7212, there are independent clocks (CLKX, CLKY, CLKM, CLKL) associated with each of these registers. The IDT7213 has only a single clock input (CLK) and three register enables. ENX and ENY control the two input registers, while ENP controls the entire product.

The IDT7212/IDT7213 offer additional flexibility with the FA control. The FA control formats the output for 2's complement by shifting the MSP up one bit and then repeating the sign bit in the MSB of the LSP.

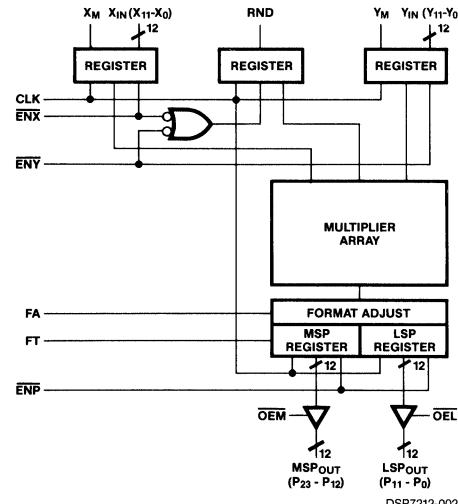
The IDT7212/IDT7213 Multipliers are 100% processed in compliance to the test methods of MIL-STD-883, Method 5004, making them ideally suited to applications demanding the highest level of performance and reliability.

FUNCTIONAL BLOCK DIAGRAMS



IDT7212

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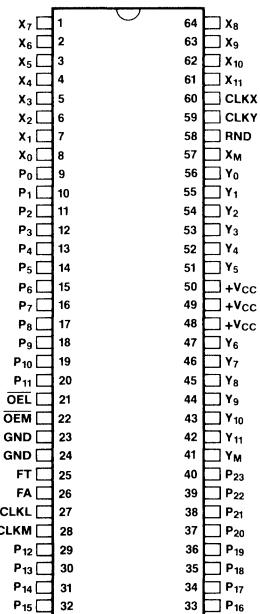


IDT7213

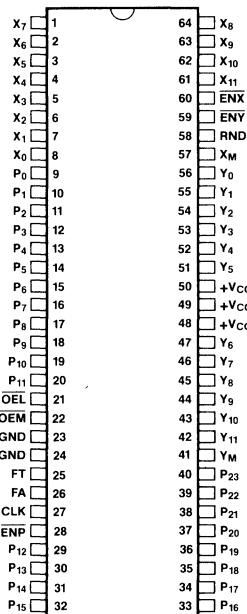
MILITARY AND COMMERCIAL TEMPERATURE RANGES

JULY 1986

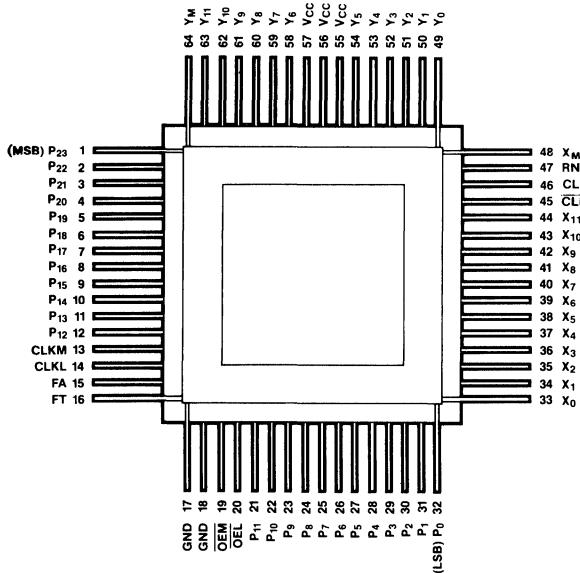
PIN CONFIGURATIONS

IDT7212
64-PIN DIP

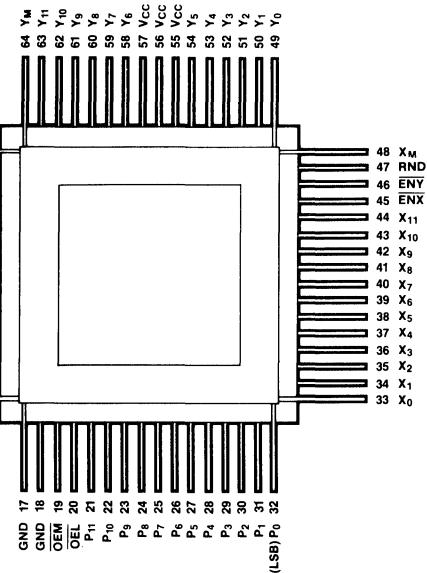
TOP VIEW DSP7212-003

IDT7213
64-PIN DIP

TOP VIEW DSP7212-004

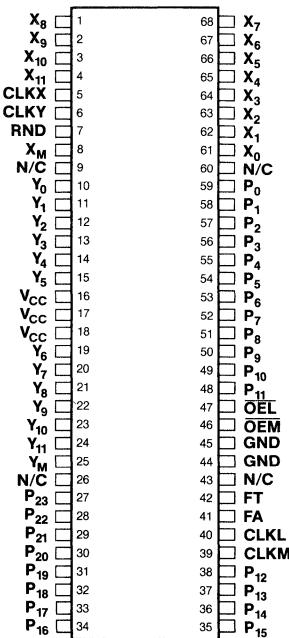
IDT7212
64-LEAD FLATPACK

TOP VIEW DSP7212-005

IDT7213
64-LEAD FLATPACK

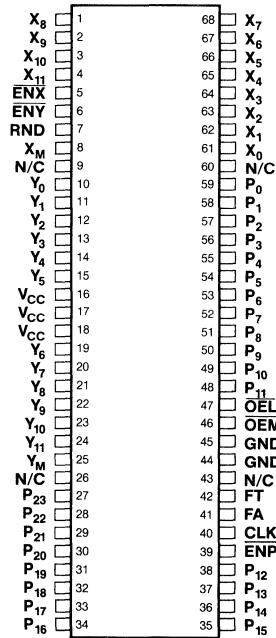
TOP VIEW DSP7212-007

IDT7212
68-PIN SHRINK-DIP



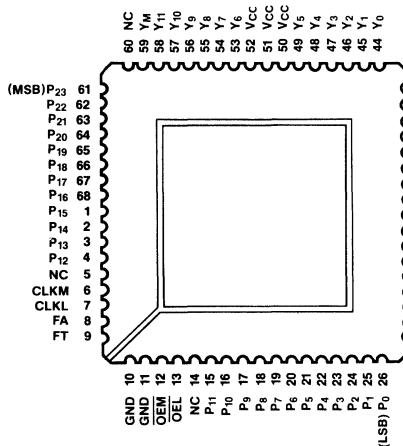
TOP VIEW

IDT7213
68-PIN SHRINK-DIP



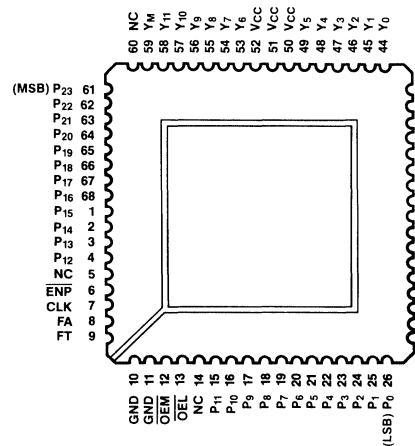
TOP VIEW

IDT7212
68-PIN LCC



TOP VIEW

IDT7213
68-PIN LCC



DSP7212-008

ABSOLUTE MAXIMUM RATING⁽¹⁾

SYMBOL	RATING	COMMERCIAL	MILITARY	UNIT
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
T _A	Operating Temperature	0 to +70	-55 to +125	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C
P _T	Power Dissipation	1.4	1.4	W
I _{OUT}	DC Output Current	50	50	mA

NOTE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS

(Commercial V_{CC} = 5V ± 10%, T_A = 0°C to +70°C , Military V_{CC} = 5V ± 10%, T_A = -55°C to +125°C) for Commercial clocked multiply times of 30,45,70ns or Military, 40,55,90ns

SYMBOL	PARAMETER	TEST CONDITIONS	COMMERCIAL MIN. TYP. ⁽¹⁾ MAX.	MILITARY MIN. TYP. ⁽¹⁾ MAX.	UNIT
I _{LL1}	Input Leakage Current	V _{CC} = Max., V _{IN} = 0 to V _{CC}	— — 10	— — 20	μA
I _{LO1}	Output Leakage Current	Hi Z, V _{CC} = Max., V _{OUT} = 0 to V _{CC}	— — 10	— — 20	μA
I _{CC} ⁽²⁾	Operating Power Supply Current	Outputs Open Measured at 10MHz ⁽²⁾	— 30 65	— 30 85	mA
I _{CCQ1}	Quiescent Power Supply Current	V _{IN} ≥ V _{IH} , V _{IN} ≤ V _{IL}	— 20 50	— 20 50	mA
I _{CCQ2}	Quiescent Power Supply Current	V _{IN} ≥ V _{CC} - 0.2V, V _{IN} ≤ 0.2V	— 4 20	— 4 25	mA
I _{CC/f} ^(2,3)	Increase in Power Supply Current/MHz	V _{CC} = Max., f > 10MHz	— — 6	— — 8	mA/ MHz
V _{OH}	Output High Voltage	V _{CC} = Min., I _{OH} = -2.0mA	2.4 — —	2.4 — —	V
V _{OL}	Output Low Voltage	V _{CC} = Min., I _{OL} = 8mA	— — 0.4	— — 0.4	V

NOTES:

1. Typical implies V_{CC} = 5V and T_A = +25°C.
2. I_{CC} is measured at 10MHz and V_{IN} = TTL voltages. For frequencies greater than 10MHz, the following equation is used for the commercial range: I_{CC} = 65 + 6(f - 10) mA, where f = operating frequency in MHz. For the military range, I_{CC} = 85 + 8(f - 10) where f = operating frequency in MHz.
3. For frequencies greater than 10MHz.

DC ELECTRICAL CHARACTERISTICS

(Commercial V_{CC} = 5V ± 10%, T_A = 0°C to +70°C , Military V_{CC} = 5V ± 10%, T_A = -55°C to +125°C) for Commercial clocked multiply times of 115ns or Military, 140ns

SYMBOL	PARAMETER	TEST CONDITIONS	COMMERCIAL MIN. TYP. ⁽¹⁾ MAX.	MILITARY MIN. TYP. ⁽¹⁾ MAX.	UNIT
I _{LL1}	Input Leakage Current	V _{CC} = Max., V _{IN} = 0 to V _{CC}	— — 2	— — 10	μA
I _{LO1}	Output Leakage Current	Hi Z, V _{CC} = Max., V _{OUT} = 0 to V _{CC}	— — 2	— — 10	μA
I _{CC} ⁽²⁾	Operating Power Supply Current	Outputs Open Measured at 10MHz ⁽²⁾	— 25 55	— 25 75	mA
I _{CCQ1}	Quiescent Power Supply Current	V _{IN} ≥ V _{IH} , V _{IN} ≤ V _{IL}	— 10 30	— 10 30	mA
I _{CCQ2}	Quiescent Power Supply Current	V _{IN} ≥ V _{CC} - 0.2V, V _{IN} ≤ 0.2V	— 0.1 1.0	— 0.1 2.0	mA
I _{CC/f} ^(2,3)	Increase in Power Supply Current/MHz	V _{CC} = Max., f > 10MHz	— — 5	— — 7	mA/ MHz
V _{OH}	Output High Voltage	V _{CC} = Min., I _{OH} = -2.0mA	2.4 — —	2.4 — —	V
V _{OL}	Output Low Voltage	V _{CC} = Min., I _{OL} = 8mA	— — 0.4	— — 0.4	V

NOTES:

1. Typical implies V_{CC} = 5V and T_A = +25°C.
2. I_{CC} is measured at 10MHz and V_{IN} = TTL voltages. For frequencies greater than 10MHz, the following equation is used for the commercial range: I_{CC} = 55 + 5(f - 10) mA, where f = operating frequency in MHz. For the military range, I_{CC} = 75 + 7(f - 10) where f = operating frequency in MHz.
3. For frequencies greater than 10MHz.

AC ELECTRICAL CHARACTERISTICS COMMERCIAL ($V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $+70^\circ C$)

SYMBOL	PARAMETER	IDT7212L30 IDT7213L30	MIN.	MAX.	IDT7212L45 IDT7213L45	MIN.	MAX.	IDT7212L70 IDT7213L70	MIN.	MAX.	IDT7212L115 IDT7213L115	MIN.	MAX.	UNITS	TEST LOAD FIG.	
t_{MUC}	Unclocked Multiply Time	—	50	—	65	—	105	—	155	—	ns	1	—	—	ns	1
t_{MC}	Clocked Multiply Time	—	30	—	45	—	70	—	115	—	ns	1	—	—	ns	1
t_S	X, Y, RND Set-Up Time	15	—	20	—	20	—	25	—	ns	1	—	—	ns	1	
t_H	X, Y, RND Hold Time	3	—	3	—	2	—	0	—	ns	1	—	—	ns	1	
t_{PWH}	Clock Pulse Width High	15	—	20	—	20	—	25	—	ns	1	—	—	ns	1	
t_{PWL}	Clock Pulse Width Low	15	—	20	—	20	—	25	—	ns	1	—	—	ns	1	
t_{PDP}	Output Clock to P	—	25	—	25	—	30	—	40	—	ns	1	—	—	ns	1
t_{ENA}	3 State Enable Time ⁽²⁾	—	25	—	30	—	35	—	40	—	ns	2	—	—	ns	2
t_{DIS}	3 State Disable Time ⁽²⁾	—	25	—	25	—	30	—	35	—	ns	2	—	—	ns	2
t_S	Clock Enable Setup Time (IDT7213 only)	15	—	20	—	25	—	25	—	ns	1	—	—	ns	1	
t_H	Clock Enable Hold Time (IDT7213 only)	3	—	3	—	3	—	0	—	ns	1	—	—	ns	1	
t_{HCL}	Clock Low Hold Time CLKXY Relative to CLKML ⁽¹⁾ (IDT7212 only)	0	—	0	—	0	—	0	—	ns	1	—	—	ns	1	

AC ELECTRICAL CHARACTERISTICS MILITARY ($V_{CC} = 5V \pm 10\%$, $T_A = -55^\circ C$ to $+125^\circ C$)

SYMBOL	PARAMETER	IDT7212L40 IDT7213L40	MIN.	MAX.	IDT7212L55 IDT7213L55	MIN.	MAX.	IDT7212L90 IDT7213L90	MIN.	MAX.	IDT7212L140 IDT7213L140	MIN.	MAX.	UNITS	TEST LOAD FIG.	
t_{MUC}	Unclocked Multiply Time	—	60	—	75	—	130	—	185	—	ns	1	—	—	ns	1
t_{MC}	Clocked Multiply Time	—	40	—	55	—	90	—	140	—	ns	1	—	—	ns	1
t_S	X, Y, RND Set-Up Time	20	—	20	—	25	—	30	—	ns	1	—	—	ns	1	
t_H	X, Y, RND Hold Time	3	—	3	—	2	—	0	—	ns	1	—	—	ns	1	
t_{PWH}	Clock Pulse Width High	20	—	25	—	30	—	30	—	ns	1	—	—	ns	1	
t_{PWL}	Clock Pulse Width Low	20	—	25	—	30	—	30	—	ns	1	—	—	ns	1	
t_{PDP}	Output Clock to P	—	25	—	30	—	35	—	45	—	ns	1	—	—	ns	1
t_{ENA}	3 State Enable Time ⁽²⁾	—	25	—	30	—	40	—	45	—	ns	2	—	—	ns	2
t_{DIS}	3 State Disable Time ⁽²⁾	—	25	—	25	—	40	—	45	—	ns	2	—	—	ns	2
t_S	Clock Enable Setup Time (IDT7213 only)	20	—	25	—	30	—	30	—	ns	1	—	—	ns	1	
t_H	Clock Enable Hold Time (IDT7213 only)	3	—	3	—	2	—	0	—	ns	1	—	—	ns	1	
t_{HCL}	Clock Low Hold Time CLKXY Relative to CLKML ⁽¹⁾ (IDT7212 only)	0	—	0	—	0	—	0	—	ns	1	—	—	ns	1	

NOTES:

1. To ensure that the correct product is entered in the output registers, new data may not be entered into the registers before the output registers have been clocked.
2. Transition is measured $\pm 500mV$ from steady state voltage with loading specified in Fig. 2.

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1 and 2

CAPACITANCE ($T_A = +25^\circ C$, $f = 1.0MHz$)

SYMBOL	PARAMETER ⁽¹⁾	CONDITIONS	TYP.	UNIT
C_{IN}	Input Capacitance	$V_{IN} = 0V$	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0V$	12	pF

NOTE:

1. This parameter is sampled and not 100% tested.

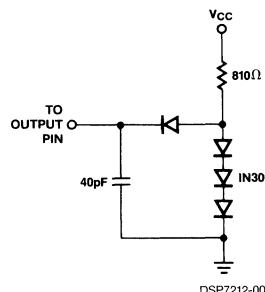
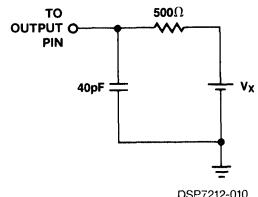
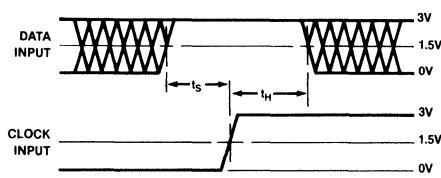


Figure 1. AC Output Test Load

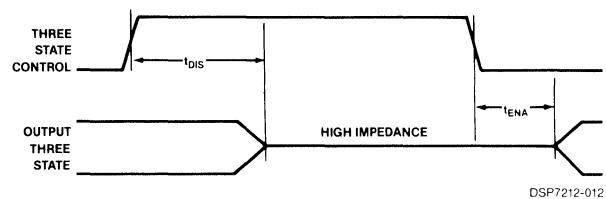
Figure 2. Output Three State Delay Load ($V_x = 0V$ or $2.6V$)



NOTE:
Diagram shown for HIGH data only. Output transition
may be opposite sense.

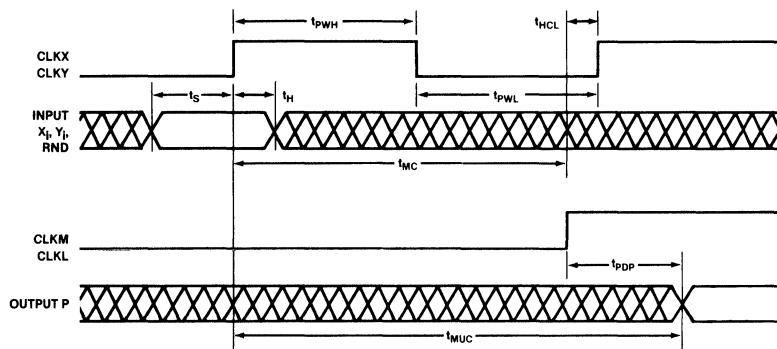
DSP7212-011

Figure 3. Set-Up And Hold Time



DSP7212-012

Figure 4. Three-State Control Timing Diagram



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Figure 5. IDT7212 Timing Diagram

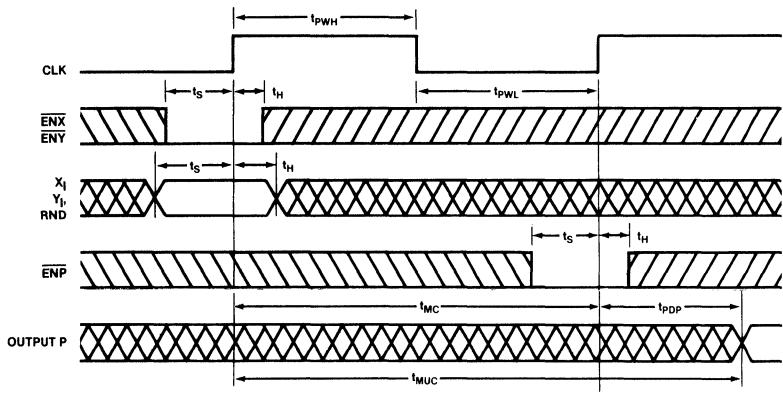
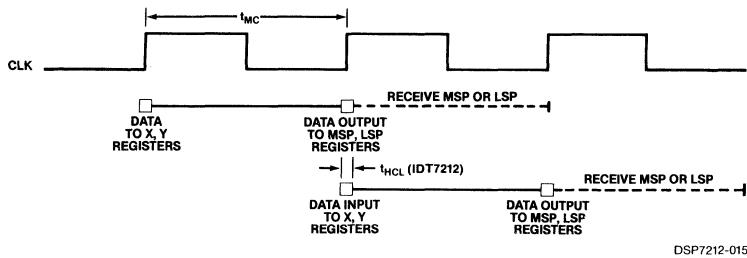


Figure 6. IDT7213 Timing Diagram



DSP7212-015

Figure 7. Simplified Timing Diagram-Typical Application

SIGNAL DESCRIPTIONS:**INPUTS:****X_{IN} (X₁₁ through X₀)**

Twelve Multiplicand Data Inputs

Y_{IN} (Y₁₁ through Y₀)

Twelve Multiplier Data Inputs

INPUT CLOCKS (IDT7212 ONLY):**CLK**

The rising edge of this clock loads the X₁₁ - X₀ data input register along with the two's complement and round registers.

CLKY

The rising edge of this clock loads the Y₁₁ - Y₀ data input register along with the two's complement and round registers.

CLKM

The rising edge of this clock loads the Most Significant Product (MSP) register.

CLKL

The rising edge of this clock loads the Least Significant Product (LSP) register.

INPUT CLOCKS (IDT7213 ONLY):**CLK**

The rising edge of this clock loads all registers.

ENX

Register enable for the X₁₁ - X₀ data input register along with the two's complement and round registers.

ENY

Register enable for the Y₁₁ - Y₀ data input register along with the two's complement and round registers.

ENP

Register enable for the Most Significant Product (MSP) and Least Significant Product (LSP).

CONTROLS:**X_M, Y_M (TCX, TCY)⁽¹⁾**

Mode control inputs for each data word. A low input designates unsigned data input with a high input used for two's complement.

NOTE:

1. TRW MPY012H/K pin designation.

FA (RS)⁽¹⁾

When the format adjust control is HIGH, a full 24-bit product is selected. When this control is LOW, a left-shifted 23-bit product is selected with the sign bit replicated in the Least Significant Product (LSP). This control is normally HIGH except for certain fractional two's complement applications. (See Multiplier Input/Output Formats.)

FT

When this control is HIGH, both the Most Significant Product (MSP) and Least Significant Product (LSP) registers are bypassed.

OEL

Three-state enable for LSP output.

OEP

Three-state enable for MSP output.

RND

Round control for the rounding of the Most Significant Product (MSP). When this control is HIGH, a one is added to the Most Significant Bit (MSB) of the Least Significant Product (LSP). Note that this bit depends on the state of the Format Adjust (FA) control. If FA is LOW when RND is HIGH, a one will be added to the P₁₀. If FA is HIGH when RND is HIGH, a one will be added to the P₁₁. In either case, the LSP output will reflect this addition when RND is HIGH. Note also the rounding always occurs in the positive direction which may introduce a systematic bias. The RND input is registered and clocked in at the rising edge of the logical OR of both CLKX and CLKY.

OUTPUTS:**MSP (P₂₃ through P₁₂)**

Most Significant Product Output

LSP (P₁₁ through P₀)

Least Significant Product Output

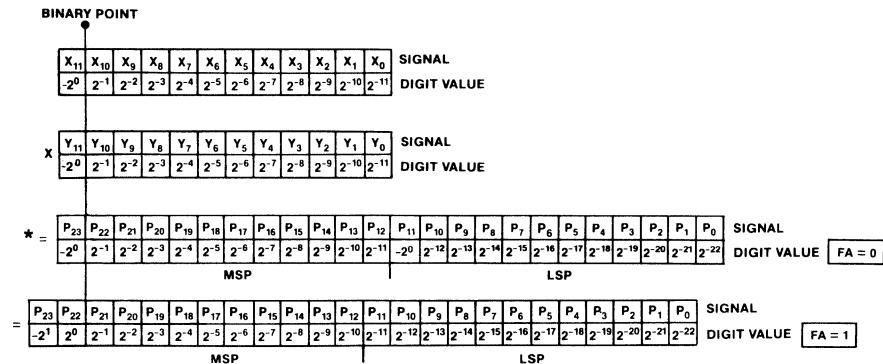


Figure 8. Fractional Two's Complement Notation

DSP7212-016

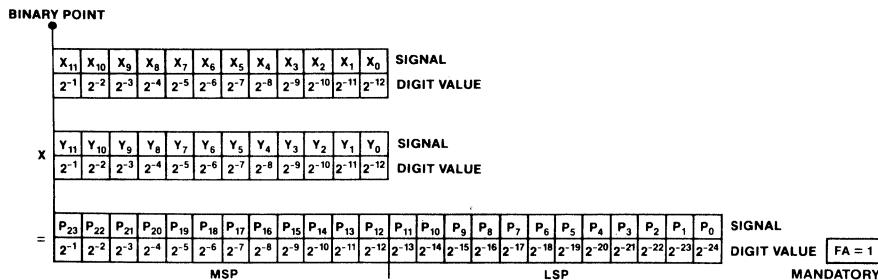


Figure 9. Fractional Unsigned Magnitude Notation

DSP7212-017

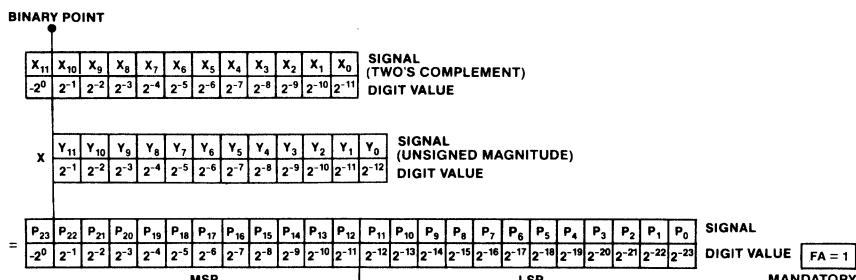


Figure 10. Fractional Mixed Mode Notation

DSP7212-018

* In this format an overflow occurs in the attempted multiplication of the two's complement number 10000 . . . 0 with 1000 . . . 00 yielding an erroneous product of -1 in the fraction case and -2²² in the integer case.

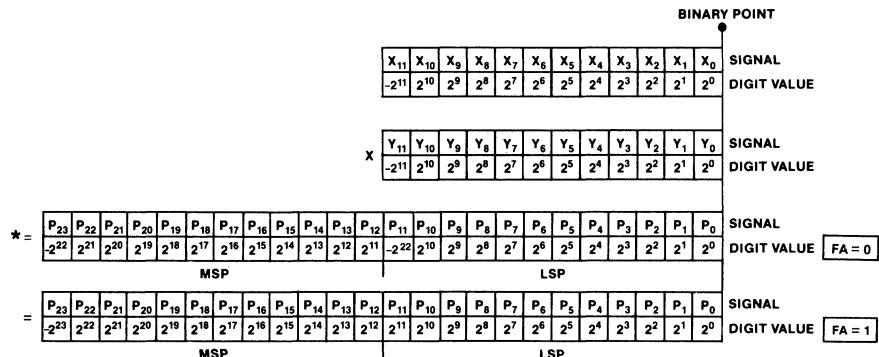


Figure 11. Integer Two's Complement Notation

DSP7212-019

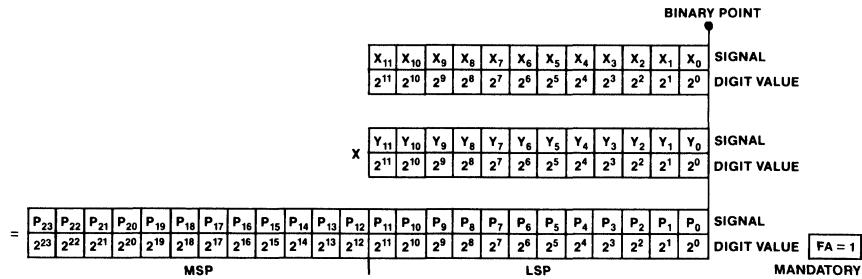


Figure 12. Integer Unsigned Magnitude Notation

DSP7212-020

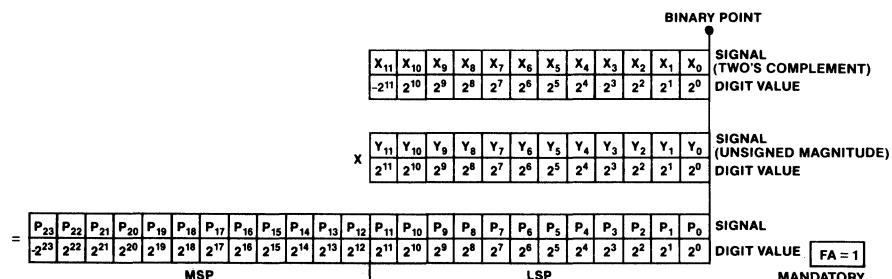


Figure 13. Integer Mixed Mode Notation

DSP7212-021

* In this format an overflow occurs in the attempted multiplication of the two's complement number 10000...0 with 1000...00 yielding an erroneous product of -1 in the fraction case and -2²² in the integer case.